

PowerMOS transistor**BUK444-800A/B****GENERAL DESCRIPTION**

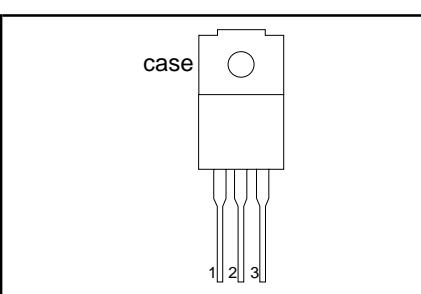
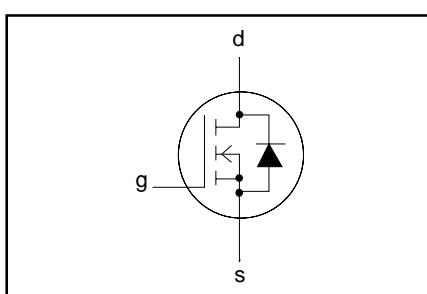
N-channel enhancement mode field-effect power transistor in a plastic full-pack envelope. The device is intended for use in Switched Mode Power Supplies (SMPS), motor control, welding, DC/DC and AC/DC converters, and in general purpose switching applications.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V_{DS}	BUK444	-800A	-800B	V
I_D	Drain-source voltage	800	800	
P_{tot}	Drain current (DC)	1.4	1.2	A
$R_{DS(ON)}$	Total power dissipation	30	30	W
	Drain-source on-state resistance	6.0	8.0	Ω

PINNING - SOT186

PIN	DESCRIPTION
1	gate
2	drain
3	source
case	isolated

PIN CONFIGURATION**SYMBOL****LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
V_{DS}	Drain-source voltage	$R_{GS} = 20 \text{ k}\Omega$	-	800		V
V_{DGR}	Drain-gate voltage		-	800		V
$\pm V_{GS}$	Gate-source voltage		-	30		V
I_D	Drain current (DC)	$T_{hs} = 25^\circ\text{C}$	-	1.4	1.2	A
I_D	Drain current (DC)		-	0.9	0.75	A
I_{DM}	Drain current (pulse peak value)		-	5.6	4.8	A
P_{tot}	Total power dissipation	$T_{hs} = 25^\circ\text{C}$	-	30		W
T_{stg}	Storage temperature		-55	150		°C
T_j	Junction Temperature		-	150		°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th(j-hs)}$	Thermal resistance junction to heatsink	with heatsink compound	-	-	4.17	K/W
$R_{th(j-a)}$	Thermal resistance junction to ambient		-	55	-	K/W

PowerMOS transistor

BUK444-800A/B

STATIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT	
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.25 \text{ mA}$	800	-	-	V	
$V_{GS(TO)}$	Gate threshold voltage	$V_{DS} = V_{GS}; I_D = 1 \text{ mA}$	2.1	3.0	4.0	V	
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 800 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25^\circ\text{C}$	-	2	20	μA	
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 800 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 125^\circ\text{C}$	-	0.1	1.0	mA	
I_{GSS}	Gate source leakage current	$V_{GS} = \pm 30 \text{ V}; V_{DS} = 0 \text{ V}$	-	10	100	nA	
$R_{DS(ON)}$	Drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 1.0 \text{ A}$	BUK444-800A	-	5.0	6.0	Ω
			BUK444-800B	-	6.0	8.0	Ω

DYNAMIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
g_{fs}	Forward transconductance	$V_{DS} = 25 \text{ V}; I_D = 1.0 \text{ A}$	1.0	2.3	-	S
C_{iss}	Input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	450	750	pF
C_{oss}	Output capacitance		-	42	70	pF
C_{rss}	Feedback capacitance		-	15	30	pF
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 30 \text{ V}; I_D = 1.9 \text{ A}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega; R_{gen} = 50 \Omega$	-	15	20	ns
t_r	Turn-on rise time		-	25	40	ns
$t_{d(off)}$	Turn-off delay time		-	50	65	ns
t_f	Turn-off fall time		-	30	40	ns
L_d	Internal drain inductance	Measured from drain lead 6 mm from package to centre of die	-	4.5	-	nH
L_s	Internal source inductance	Measured from source lead 6 mm from package to source bond pad	-	7.5	-	nH

ISOLATION LIMITING VALUE & CHARACTERISTIC $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	Repetitive peak voltage from all three terminals to external heatsink	R.H. $\leq 65\%$; clean and dustfree	-		1500	V
C_{isol}	Capacitance from T2 to external heatsink	$f = 1 \text{ MHz}$	-	12	-	pF

REVERSE DIODE LIMITING VALUES AND CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{DR}	Continuous reverse drain current	-	-	-	1.4	A
I_{DRM}	Pulsed reverse drain current	-	-	-	5.6	A
V_{SD}	Diode forward voltage	$I_F = 1.4 \text{ A}; V_{GS} = 0 \text{ V}$	-	1.0	1.3	V
t_{rr}	Reverse recovery time	$I_F = 1.4 \text{ A}; -dI_F/dt = 100 \text{ A}/\mu\text{s}; V_{GS} = 0 \text{ V}; V_R = 100 \text{ V}$	-	230	-	ns
Q_{rr}	Reverse recovery charge		-	1.9	-	μC